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**APPLICANTS**

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**\*\* CONTINUING DATA \*\*\*\*\***

*Like* This application is a 371 of PCT/JP03/03705 03/26/2003

**\*\* FOREIGN APPLICATIONS \*\*\*\*\***

JAPAN 2002-090493 03/28/2002

*Like*

Foreign Priority claimed <input checked="" type="checkbox"/> yes <input type="checkbox"/> no	<b>STATE OR COUNTRY</b> JAPAN	<b>SHEETS DRAWING</b> 0	<b>TOTAL CLAIMS</b> 4	<b>INDEPENDENT CLAIMS</b> 2
35 USC 119 (a-d) conditions met <input type="checkbox"/> yes <input checked="" type="checkbox"/> no <input type="checkbox"/> Met after				
Verified and Acknowledged	Allowance <i>Steven Loke</i> Examiner's Signature	<i>LL</i> Initials		

**ADDRESS**

21839

**TITLE**

Pressure sensitive adhesive film for protection of semiconductor wafer surface and method of protecting semiconductor wafer with the pressure sensitive adhesive film

<b>FILING FEE RECEIVED</b> 920	FEES: Authority has been given in Paper No. _____ to charge/credit DEPOSIT ACCOUNT No. _____ for following:	<input type="checkbox"/> All Fees
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